



# SOT668-2

plastic rectangular-DIL-bent-SIL (reverse bent) power package; 17 leads (row spacing 2.54 mm)

8 February 2016

Package information

## 1. Package summary

|                                       |                                 |
|---------------------------------------|---------------------------------|
| <b>Terminal position code</b>         | Z (zig-zag)                     |
| <b>Package type descriptive code</b>  | RDBS17P                         |
| <b>Package type industry code</b>     | RDBS17P                         |
| <b>Package style descriptive code</b> | RDBS (right-angle DIL-bent-SIL) |
| <b>Package style suffix code</b>      | P (power)                       |
| <b>Package body material type</b>     | P (plastic)                     |
| <b>Mounting method type</b>           | T (through-hole mount)          |
| <b>Issue date</b>                     | 12-3-2003                       |

Table 1. Package summary

| Symbol         | Parameter                      | Min  | Typ | Nom  | Max  | Unit |
|----------------|--------------------------------|------|-----|------|------|------|
| D              | package length                 | 23.6 | -   | 23.7 | 24   | mm   |
| E              | package width                  | 11.8 | -   | 12   | 12.2 | mm   |
| A <sub>2</sub> | package height                 | 4.4  | -   | 4.4  | 4.6  | mm   |
| n <sub>2</sub> | actual quantity of termination | -    | -   | 17   | -    |      |

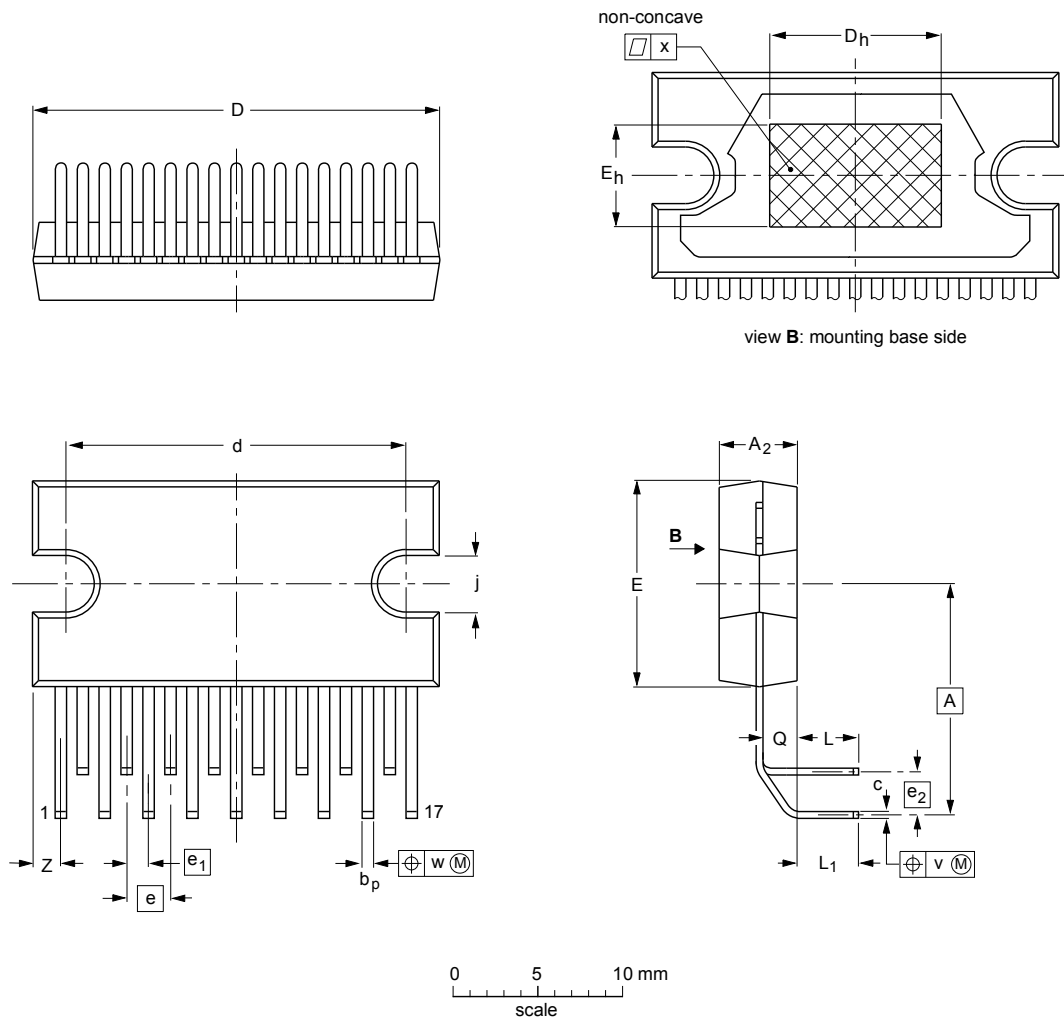


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## 2. Package outline

RDBS17P: plastic rectangular-DIL-bent-SIL (reverse bent) power package; 17 leads  
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**DIMENSIONS** (mm are the original dimensions)

| UNIT | A    | A <sub>2</sub> | b <sub>p</sub> | c            | D <sup>(1)</sup> | d            | D <sub>h</sub> | E <sup>(1)</sup> | e    | e <sub>1</sub> | e <sub>2</sub> | E <sub>h</sub> | j          | L            | L <sub>1</sub> | Q          | v   | w   | x    | Z <sup>(1)</sup> |
|------|------|----------------|----------------|--------------|------------------|--------------|----------------|------------------|------|----------------|----------------|----------------|------------|--------------|----------------|------------|-----|-----|------|------------------|
| mm   | 13.5 | 4.6<br>4.4     | 0.75<br>0.60   | 0.48<br>0.38 | 24.0<br>23.6     | 20.0<br>19.6 | 10             | 12.2<br>11.8     | 2.54 | 1.27           | 2.54           | 6              | 3.4<br>3.1 | 3.75<br>3.15 | 3.75<br>3.15   | 2.1<br>1.9 | 0.6 | 0.4 | 0.03 | 2.00<br>1.45     |

**Note**

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

| OUTLINE VERSION | REFERENCES |       |       |  | EUROPEAN PROJECTION | ISSUE DATE             |
|-----------------|------------|-------|-------|--|---------------------|------------------------|
|                 | IEC        | JEDEC | JEITA |  |                     |                        |
| SOT668-2        |            |       |       |  |                     | -01-01-05-<br>03-03-12 |

Fig. 1. Package outline RDBS17P (SOT668-2)

### 3. Legal information

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